

DUAL CHANNEL POWER DRIVER

FEATURES

- Two Independent Drivers
- 1.5 A Totem Pole Outputs
- Inverting and Non-Inverting Inputs
- 40 ns Rise and Fall Into 1000 pF
- High-Speed, Power MOSFET Compatible
- Low Cross-Conduction Current Spike
- Analog Shutdown With Optional Latch
- Low Quiescent Current
- 5 V to 40 V Operation
- Thermal Shutdown Protection
- 16-Pin Dual-In-Line Package
- 20-Pin PLCC and CLCC Package

DESCRIPTION

The UC1707 family of power drivers is made with a high-speed Schottky process to interface between low-level control functions and high-power switching devices—particularly power MOSFETs. These devices contain two independent channels, each of which can be activated by either a high or low input logic level signal. Each output can source or sink up to 1.5 A as long as power dissipation limits are not exceeded.

Although each output can be activated independently with its own inputs, it can be forced low in common through the action either of a digital high signal at the Shutdown terminal or a differential low-level analog signal. The Shutdown command from either source can either be latching or not, depending on the status of the Latch Disable pin.

Supply voltage for both V_{IN} and V_C can independently range from 5 V to 40 V.

These devices are available in two-watt plastic "bat-wing" DIP for operation over a 0°C to 70°C temperature range and, with reduced power, in a hermetically sealed cerdip for –55°C to +125°C operation. Also available in surface mount DW, Q, L packages.

TRUTH TABLE
(Each Channel)⁽¹⁾

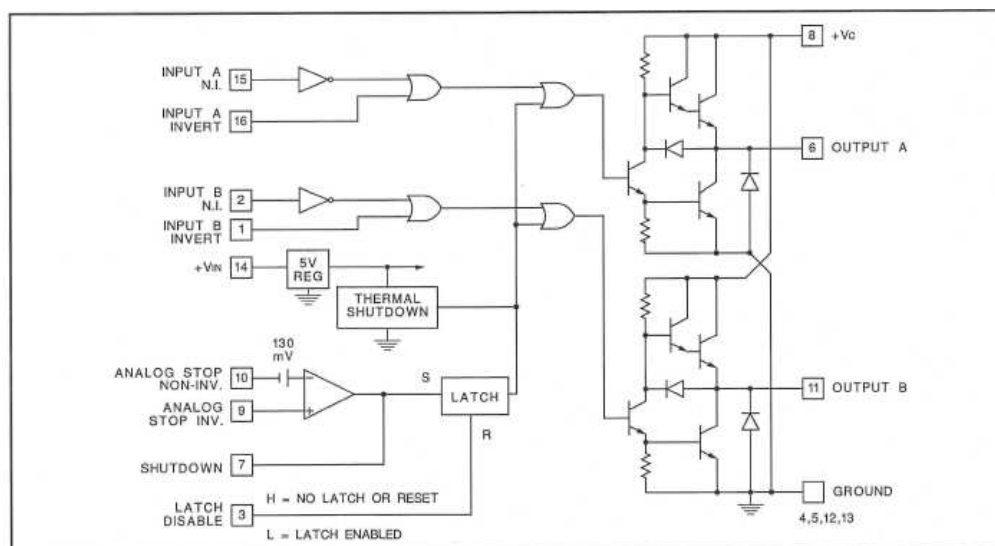
INV.	N.I.	OUT
H	H	L
L	H	H
H	L	L
L	L	L

(1) $\overline{OUT} = \overline{INV}$ and N.I.
 $\overline{OUT} = INV$ or N.I.

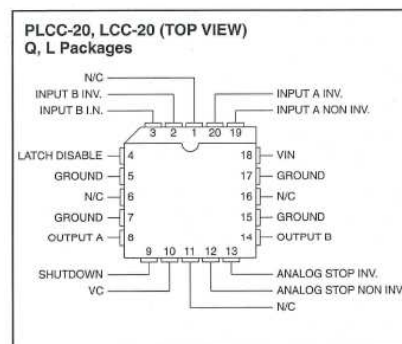
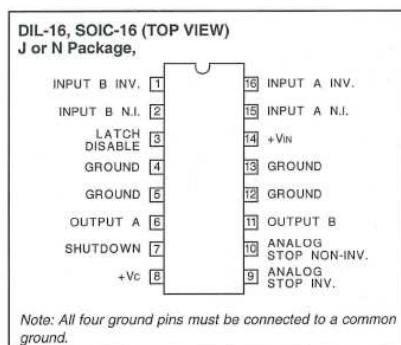


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BLOCK DIAGRAM



CONNECTION DIAGRAMS



ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{IN}	Supply voltage	N/J package		40	V
V_C	Collector supply voltage	N/J package		40	V
	Output current (each output, source or sink) steady-state	N/J package		±500	mA
	Peak transient	N package		±1.5	A
		J package		±1.0	
	Capacitive discharge energy	N package		20	mJ
		J package		15	
	Digital inputs ⁽¹⁾	N/J-package		5.5	V
	Analog stop inputs	N/J package		V_{IN}	
	Power dissipation at $T_A = 25^\circ\text{C}$	N package		2	W
		J package		1	
	Power dissipation at T (leads/case) = 25°C ⁽¹⁾	N package		5	W
		J package		2	
	Operating temperature range		–55	+125	$^\circ\text{C}$
	Storage temperature range		–65	+150	$^\circ\text{C}$
	Lead temperature (soldering, 10 seconds)			300	$^\circ\text{C}$

- (1) All voltages are with respect to the four ground pins which must be connected together. All currents are positive into, negative out of the specified terminal. Digital drive can exceed 5.5 V if input current is limited to 10 mA. Consult packaging section of databook for thermal limitations and considerations of package.

ELECTRICAL CHARACTERISTICS

Unless otherwise stated, these specifications apply for $T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$ for the UC1707, -25°C to $+85^\circ\text{C}$ for the UC2707, and 0°C to $+70^\circ\text{C}$ for the UC3707; $V_{IN} = V_C = 20\text{ V}$. $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IN} Supply current	$V_{IN} = 40\text{ V}$		12	15	mA
V_C Supply current	$V_C = 40\text{ V}$, outputs low		5.2	7.5	mA
V_C Leakage current	$V_{IN} = 0$, $V_C = 30\text{ V}$, no load		0.05	0.1	mA
Digital input low level				0.8	V
Digital input high level		2.2			V
Input current	$V_I = 0$	–0.06		–1.0	mA
Input leakage	$V_I = 5\text{ V}$		0.05	0.1	mA
$V_C - V_O$ Output high sat.	$I_O = -50\text{ mA}$			2.0	V
	$I_O = -500\text{ mA}$			2.5	
V_O Output low sat.	$I_O = -50\text{ mA}$			0.4	V
	$I_O = -500\text{ mA}$			2.5	
Analog threshold	$V_{CM} = 0$ to 15 V	100	130	160	mV
Input bias current	$V_{CM} = 0$		–10	–20	μA
Thermal shutdown			155		$^\circ\text{C}$
Shutdown threshold	Pin 7 input	0.4	1.0	2.2	V
Latch disable threshold	Pin 3 input	0.8	1.2	2.2	V

TYPICAL SWITCHING CHARACTERISTICS

$V_{IN} = V_C = 20\text{ V}$, $T_A = 25^\circ\text{C}$. Delays measured to 10% output change.

PARAMETER	TEST CONDITIONS	OUTPUT CL =			UNIT
From Inv. Input to Output		open	1.0	2.2	nF
Rise time delay		40	50	60	ns
10% to 90% rise		25	40	50	ns
Fall time delay		30	40	50	ns
90% to 10% fall		25	40	50	ns
From N.I. Input to Output					
Rise time delay		30	40	50	ns
10% to 90% rise		25	40	50	ns
Fall time delay		45	55	65	ns
90% to 10% fall		25	40	50	ns
V_C cross-conduction current spike duration	Output rise	25			ns
	Output fall	0			ns
Analog shutdown delay	Stop non-Inv. = 0 V	180			ns
	Stop Inv. = 0 to 0.5 V	180			ns
Digital shutdown delay	2 V input on Pin 7	50			ns

SIMPLIFIED INTERNAL CIRCUITRY

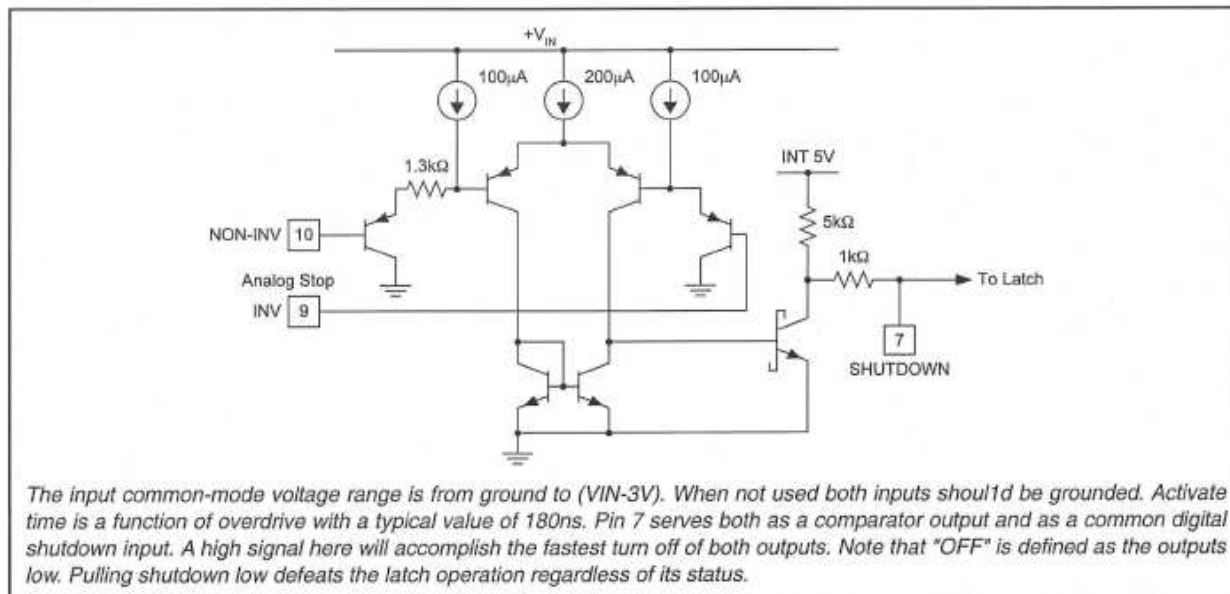


Figure 1. Typical Digital Input Gate

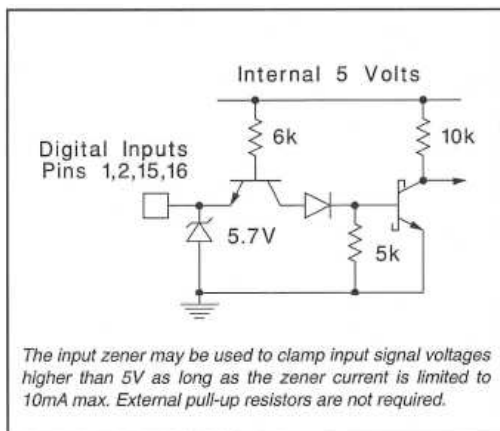


Figure 2. Typical Digital Input Gate

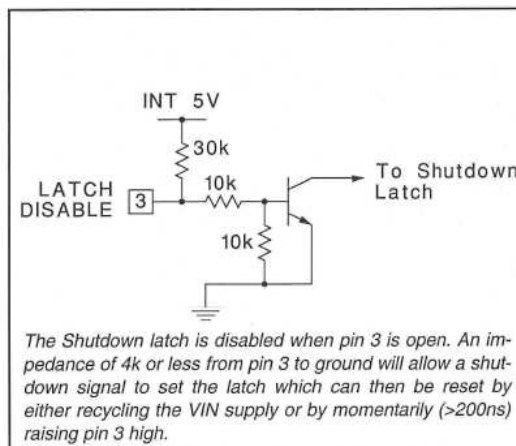
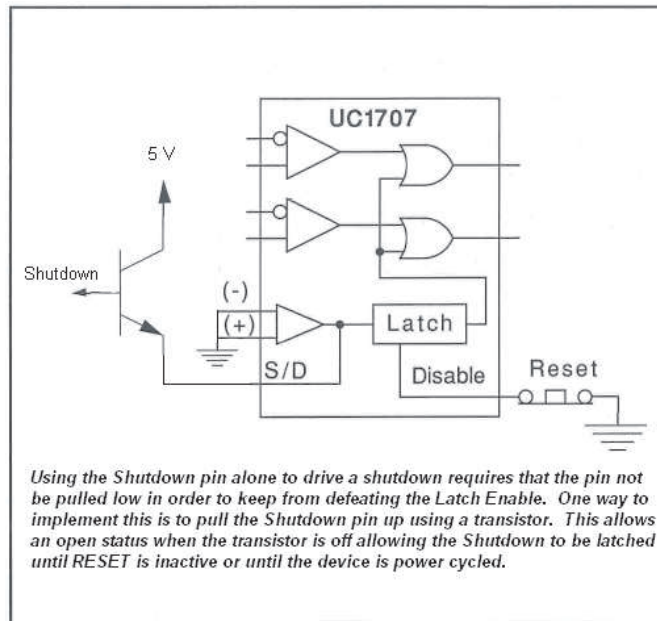


Figure 3. Latch Disable

SIMPLIFIED INTERNAL CIRCUITRY (continued)**Figure 4. Use of the Shutdown Pin****SHUTDOWN CIRCUIT DESCRIPTION**

The function of the circuitry is to be able to provide a shutdown of the device. This is defined as functionality that will drive both outputs to the low state. There are three different inputs that govern this shutdown capability.

- **Analog Stop Pins** — The differential inputs to this comparator provide a way to execute a shutdown.
- **Latch Disable Pin** — Assuming that the Shutdown pin is left open, a high on this pin disables the latching functionality of the Analog Stop shutdown. A low on this pin enables the latching functionality of the Analog Stop shutdown. If a shutdown occurs through the Analog Stop circuit while Latch Disable is high, then the outputs will go low, but will return to normal operation as soon as the Analog Stop circuit allows it. If a shutdown occurs through the Analog Stop circuit while Latch Disable is low, then the outputs will go low and remain low even if the Analog Stop circuit no longer drives the shutdown. The outputs will remain "latched" low (in shutdown) until the Latch Disable goes high and the Analog Stop circuit allows it to return from shutdown or the VIN voltage is cycled to 0V and then returned above 5V.
- **Shutdown Pin** — This pin serves two purposes.
 1. It can be used as an output of the Analog Stop circuit.
 2. It can be used as an input to force a shutdown or to force the device out of shutdown. This pin can override both the Analog Stop circuit as well as the Latch Disable Pin. When driving hard logic levels into the Shutdown pin, the Latch Disable functionality will be overridden and the Latch Disable will not function as it does when used in conjunction with the Analog Stop circuit. When the Shutdown pin is high, the outputs will be in the low state (shutdown). When the Shutdown pin is low (hard logic low) the outputs will operate normally, regardless of the state of the Latch Disable pin or the Analog Stop pins.

In order to use the Shutdown Pin with the Latch Disable functional it is necessary to use either a diode in series with the Shutdown signal or to use an open collector pull-up so that the Shutdown pin is not pulled low. This configuration will allow the Latch Disable function to work with the Shutdown pin.

SIMPLIFIED INTERNAL CIRCUITRY (continued)

UG1707 SHUTDOWN TRUTH TABLE

ANALOG STOP LOGIC	SHUTDOWN	LATCH DISABLE	PREVIOUS STATE OF OUTPUT	OUTPUT
X	0	X	X	Follows Input Logic
X	1	X	X	Low (Shutdown)
1	Open	X	X	Low (Shutdown)
0	Open	0	Shutdown	⁽¹⁾ Latched Shutdown
0	Open	0	Normal	Follows Input Logic
0	Open	1	X	Follows Input Logic

- (1) If the output was previously in Shutdown and Latch Disable was low and stays low, then even if the Analog Stop Logic is changed or the Shutdown pin is open, the outputs will remain in Shutdown.

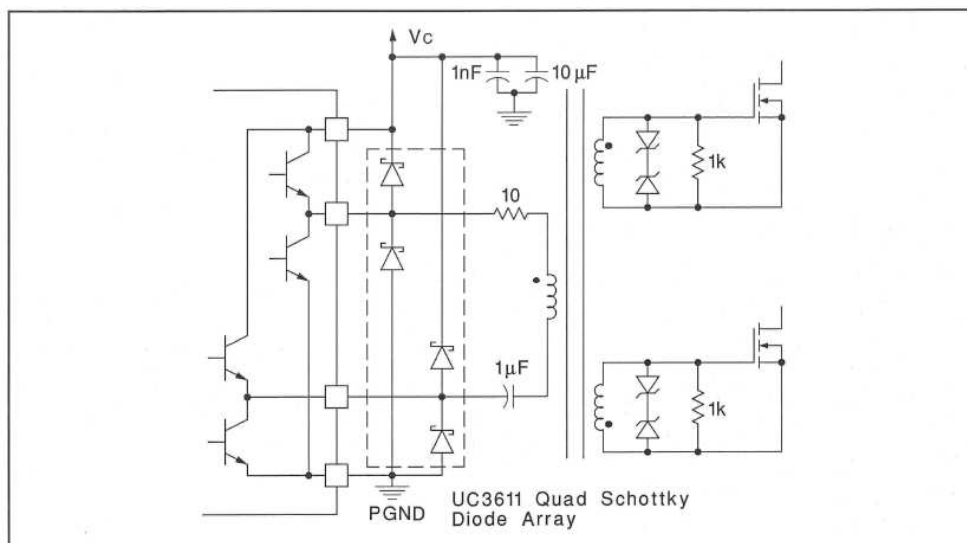


Figure 5. Transformer Coupled Push-Pull MOSFET Drive Circuit

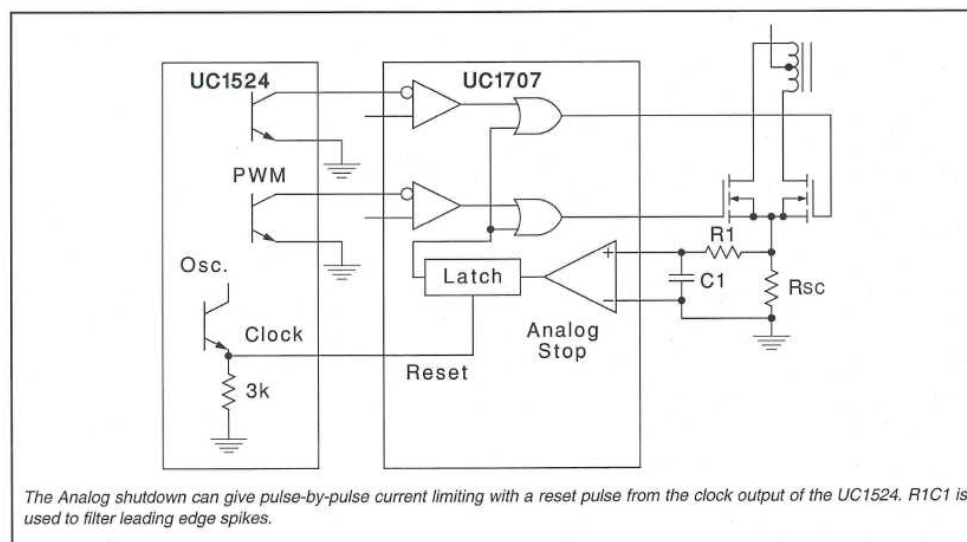


Figure 6. Current Limiting

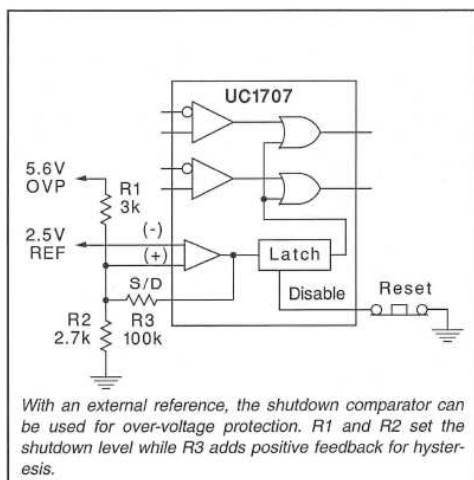


Figure 7. Over-Voltage Protection

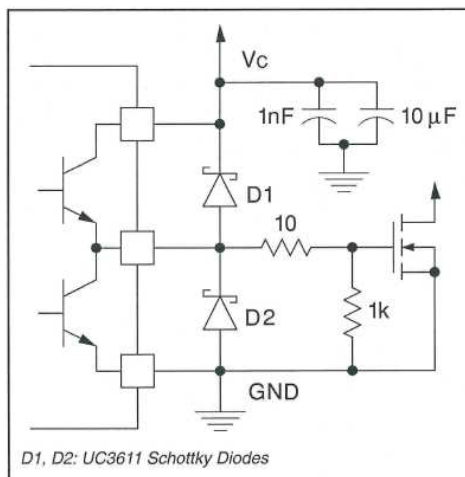


Figure 8. Power MOSFET Drive Circuit

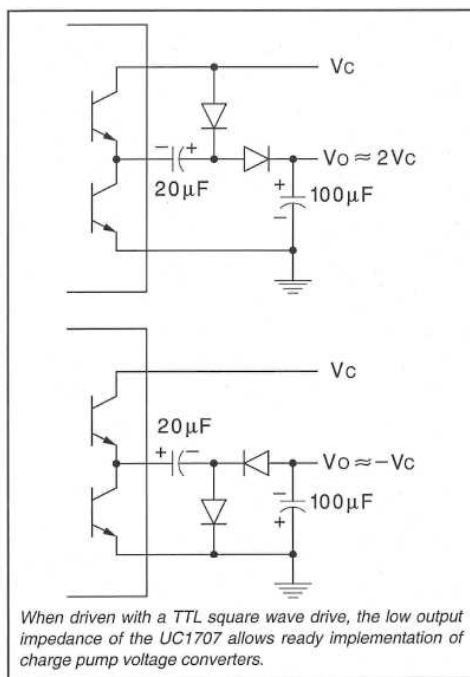


Figure 9. Charge Pump Circuits

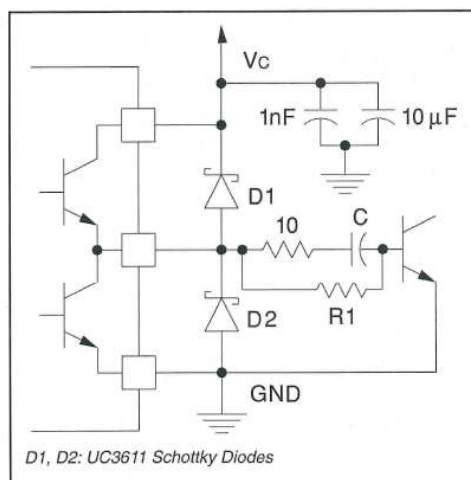


Figure 10. Power Bipolar Drive Circuit

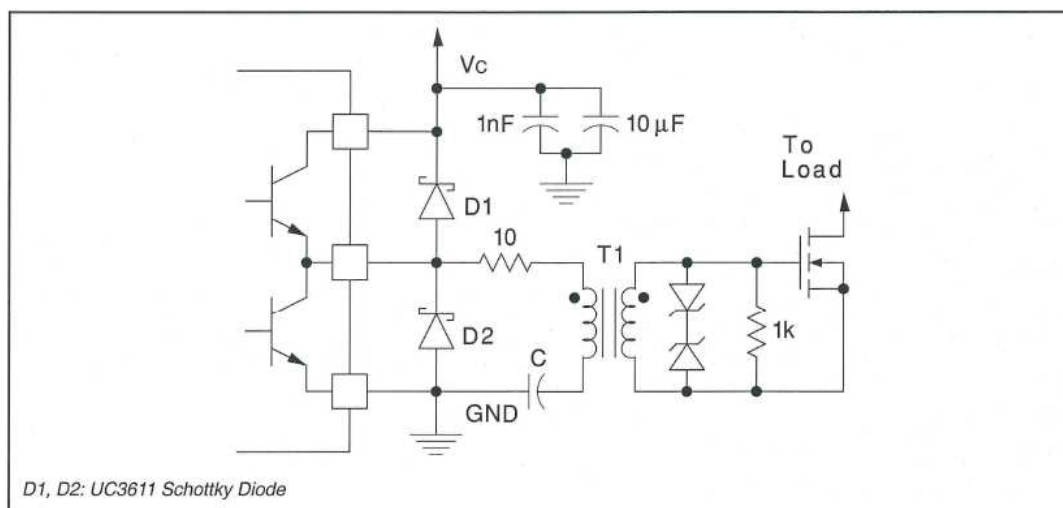


Figure 11. Transformer Coupled MOSFET Drive Circuit

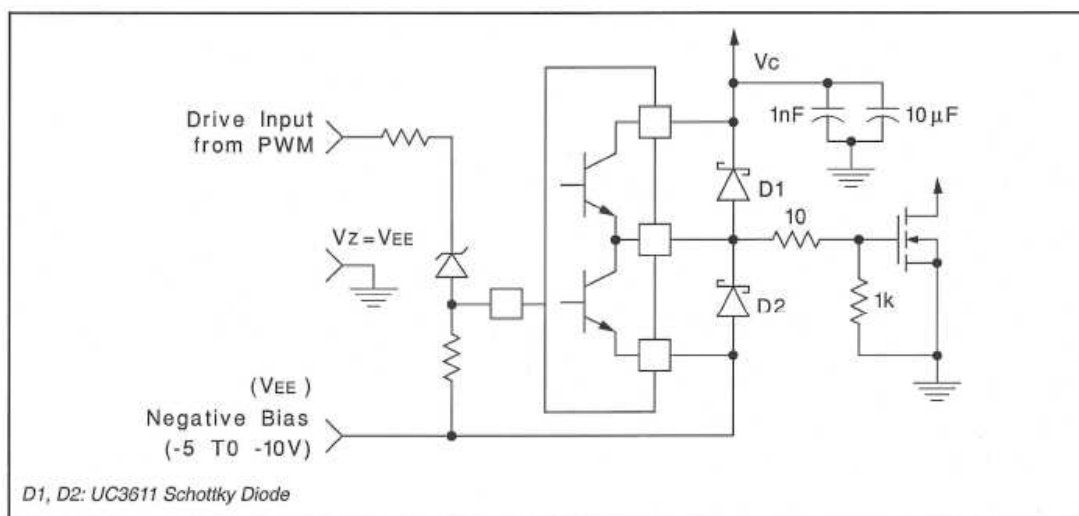


Figure 12. Power MOSFET Drive Circuit Using Negative Bias Voltage and Level Shifting to Ground Reference PWM

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-87619012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87619012A UC1707L/ 81032
5962-87619012A.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87619012A UC1707L/ 81032
5962-8761901EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8761901EA UC1707J/80900
5962-8761901EA.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8761901EA UC1707J/80900
UC1707J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1707J
UC1707J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1707J
UC1707J883B	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1707J/883B
UC1707J883B.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1707J/883B
UC1707L	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1707L
UC1707L.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1707L
UC1707L883B	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1707L/ 883B
UC1707L883B.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1707L/ 883B
UC2707DW	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2707DW
UC2707DW.A	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2707DW
UC2707DWTR	Active	Production	SOIC (DW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2707DW
UC2707DWTR.A	Active	Production	SOIC (DW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2707DW
UC2707N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	UC2707N
UC2707N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	UC2707N
UC2707NG4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	UC2707N
UC3707DW	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3707DW
UC3707DW.A	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3707DW
UC3707DWTR	Active	Production	SOIC (DW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3707DW

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
UC3707DWTR.A	Active	Production	SOIC (DW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3707DW
UC3707J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	0 to 70	UC3707J
UC3707J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	0 to 70	UC3707J
UC3707N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UC3707N
UC3707N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UC3707N
UC3707NG4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UC3707N

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF UC1707, UC3707, UC3707M :

- Catalog : [UC3707](#), [UC3707M](#), [UC3707](#)
- Military : [UC1707](#), [UC1707](#)
- Space : [UC1707-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2707DWTR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
UC3707DWTR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

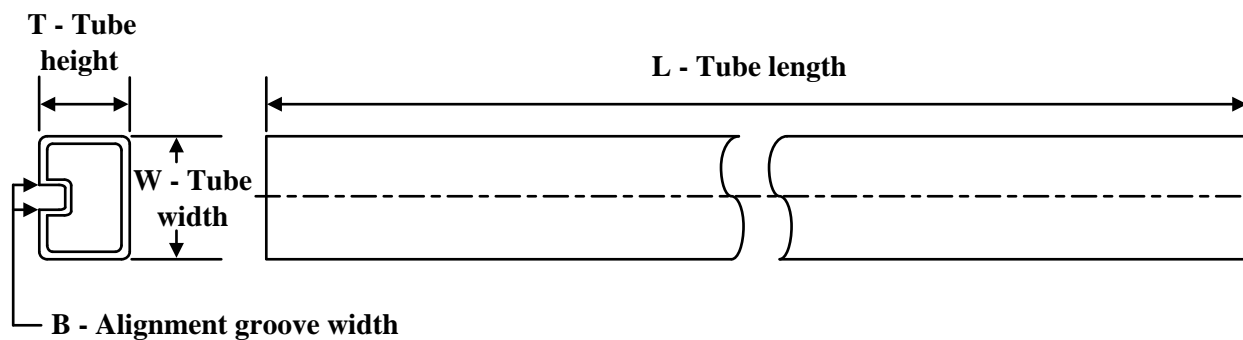
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2707DWTR	SOIC	DW	16	2000	353.0	353.0	32.0
UC3707DWTR	SOIC	DW	16	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-87619012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-87619012A.A	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1707L	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1707L.A	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1707L883B	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1707L883B.A	FK	LCCC	20	55	506.98	12.06	2030	NA
UC2707DW	DW	SOIC	16	40	507	12.83	5080	6.6
UC2707DW.A	DW	SOIC	16	40	507	12.83	5080	6.6
UC2707N	N	PDIP	16	25	506	13.97	11230	4.32
UC2707N.A	N	PDIP	16	25	506	13.97	11230	4.32
UC2707NG4	N	PDIP	16	25	506	13.97	11230	4.32
UC3707DW	DW	SOIC	16	40	507	12.83	5080	6.6
UC3707DW.A	DW	SOIC	16	40	507	12.83	5080	6.6
UC3707N	N	PDIP	16	25	506	13.97	11230	4.32
UC3707N.A	N	PDIP	16	25	506	13.97	11230	4.32
UC3707NG4	N	PDIP	16	25	506	13.97	11230	4.32

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